Preferred Device

# **Dual Common Base-Collector Bias Resistor Transistors**

## NPN and PNP Silicon Surface Mount Transistors with Monolithic Bias Resistor Network

The BRT (Bias Resistor Transistor) contains a single transistor with a monolithic bias network consisting of two resistors; a series base resistor and a base-emitter resistor. These digital transistors are designed to replace a single device and its external resistor bias network. The BRT eliminates these individual components by integrating them into a single device. In the NSB1010XV5T5, two complementary BRT devices are housed in the SOT-553 package which is ideal for low power surface mount applications where board space is at a premium.

- Simplifies Circuit Design
- Reduces Board Space
- Reduces Component Count
- Available in 8 mm, 7 inch Tape and Reel
- This device is manufactured with a Pb-Free external lead finish only.

**MAXIMUM RATINGS** ( $T_A = 25^{\circ}C$  unless otherwise noted, common for  $Q_1$  and  $Q_2$ , – minus sign for  $Q_1$  (PNP) omitted)

Rating	Symbol	Value	Unit
Collector-Base Voltage	$V_{CBO}$	50	Vdc
Collector-Emitter Voltage	$V_{CEO}$	50	Vdc
Collector Current	I <sub>C</sub>	100	mAdc

#### THERMAL CHARACTERISTICS

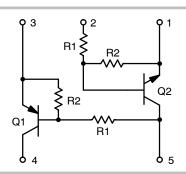
Characteristic (One Junction Heated)	Symbol	Max	Unit
Total Device Dissipation  T <sub>A</sub> = 25°C  Derate above 25°C	P <sub>D</sub>	357 (Note 1) 2.9 (Note 1)	mW mW/°C
Thermal Resistance Junction-to-Ambient	$R_{\theta JA}$	350 (Note 1)	°C/W
Characteristic (Both Junctions Heated)	Symbol	Max	Unit
Total Device Dissipation  T <sub>A</sub> = 25°C  Derate above 25°C	P <sub>D</sub>	500 (Note 1) 4.0 (Note 1)	mW mW/°C
Thermal Resistance Junction-to-Ambient	$R_{\theta JA}$	250 (Note 1)	°C/W
Junction and Storage Temperature	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. FR-4 @ Minimum Pad.



#### http://onsemi.com









US = Specific Device Code

D = Date Code

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NSB1010XV5T5	SOT-553 (Pb-Free)	2 mm pitch 8000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

**Preferred** devices are recommended choices for future use and best overall value.

### **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
Q1 TRANSISTOR: PNP OFF CHARACTERISTICS					
Collector-Base Cutoff Current (V <sub>CB</sub> = -50 V, I <sub>E</sub> = 0)	Ісво	-	_	-100	nAdc
Collector-Emitter Cutoff Current ( $V_{CB} = -50 \text{ V}, I_B = 0$ )	I <sub>CEO</sub>	-	_	-500	nAdc
Emitter-Base Cutoff Current ( $V_{EB} = -6.0 \text{ V}, I_{C} = 0$ )	I <sub>EBO</sub>	-	_	-1.5	mAdc
Collector-Base Breakdown Voltage ( $I_C = -10 \mu A, I_E = 0$ )	V <sub>(BR)CBO</sub>	-50	_	-	Vdc
Collector-Emitter Breakdown Voltage (Note 2) (I <sub>C</sub> = -2.0 mA, I <sub>B</sub> = 0)	V <sub>(BR)CEO</sub>	-50	_	_	Vdc
ON CHARACTERISTICS (Note 2)					
Collector-Emitter Saturation Voltage (I <sub>C</sub> = −10 mA, I <sub>B</sub> = −1.0 mA)	V <sub>CE(sat)</sub>	_	_	-0.25	Vdc
DC Current Gain (V <sub>CE</sub> = -10 V, I <sub>C</sub> = -5.0 mA)	h <sub>FE</sub>	15	27	_	_
Output Voltage (on) ( $V_{CC}$ = -5.0 V, $V_B$ = -2.5 V, $R_L$ = 1.0 k $\Omega$ )	V <sub>OL</sub>	_	-	-0.2	Vdc
Output Voltage (off) ( $V_{CC}$ = -5.0 V, $V_B$ = -0.5 V, $R_L$ = 1.0 k $\Omega$ )	V <sub>OH</sub>	-4.9	_	_	Vdc
Input Resistor	R <sub>1</sub>	3.3	4.7	6.1	kΩ
Resistor Ratio	R <sub>1</sub> /R <sub>2</sub>	0.8	1.0	1.2	-
Q2 TRANSISTOR: NPN OFF CHARACTERISTICS					
Collector-Base Cutoff Current (V <sub>CB</sub> = 50 V, I <sub>E</sub> = 0)	I <sub>CBO</sub>	_	_	100	nAdc
Collector-Emitter Cutoff Current (V <sub>CB</sub> = 50 V, I <sub>B</sub> = 0)	I <sub>CEO</sub>	-	-	500	nAdc
Emitter-Base Cutoff Current (V <sub>EB</sub> = 6.0, I <sub>C</sub> = 5.0 mA)	I <sub>EBO</sub>	_	_	0.5	mAdc
ON CHARACTERISTICS					
Collector-Base Breakdown Voltage ( $I_C = 10 \mu A, I_E = 0$ )	V <sub>(BR)CBO</sub>	50	_	_	Vdc
Collector-Emitter Breakdown Voltage (I <sub>C</sub> = 2.0 mA, I <sub>B</sub> = 0)	V <sub>(BR)CEO</sub>	50	_	-	Vdc
DC Current Gain (V <sub>CE</sub> = 10 V, I <sub>C</sub> = 5.0 mA)	h <sub>FE</sub>	35	60	-	
Collector-Emitter Saturation Voltage ( $I_C$ = 10 mA, $I_B$ = 0.3 mA)	V <sub>CE(SAT)</sub>	-	-	0.25	Vdc
Output Voltage (on) (V $_{CC}$ = 5.0 V, V $_{B}$ = 2.5 V, R $_{L}$ = 1.0 k $\Omega$ )	V <sub>OL</sub>	-	-	0.2	Vdc
Output Voltage (off) (V <sub>CC</sub> = 5.0 V, V <sub>B</sub> = 0.5 V, R <sub>L</sub> = 1.0 k $\Omega$ )	V <sub>OH</sub>	4.9	-	-	Vdc
Input Resistor	R1	7.0	10	13	kΩ
Resistor Ratio	R1/R2	0.8	1.0	1.2	-

<sup>2.</sup> Pulse Test: Pulse Width < 300 μs, Duty Cycle < 2.0%.

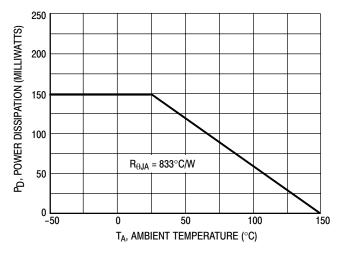


Figure 1. Derating Curve

#### TYPICAL ELECTRICAL CHARACTERISTICS — PNP TRANSISTOR

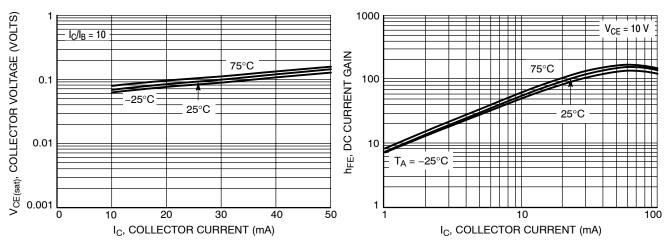


Figure 2.  $V_{CE(sat)}$  versus  $I_C$ 

Figure 3. DC Current Gain

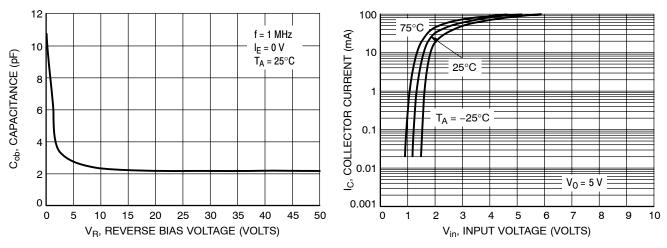


Figure 4. Output Capacitance

Figure 5. Output Current versus Input Voltage

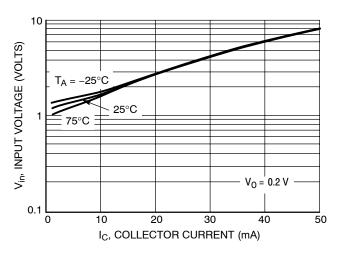
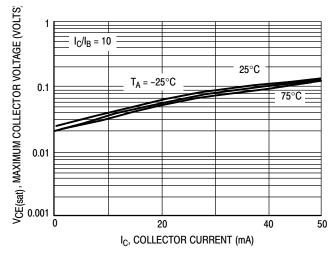


Figure 6. Input Voltage versus Output Current

#### TYPICAL ELECTRICAL CHARACTERISTICS — NPN TRANSISTOR

1000

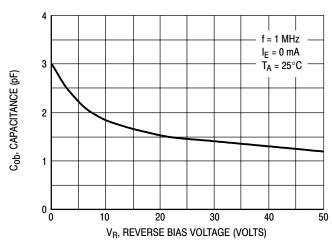


T<sub>A</sub> = 75°C - 25°C - 25°C - 25°C - 25°C | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 | 100 |

 $V_{CE} = 10 V$ 

Figure 7.  $V_{CE(sat)}$  versus  $I_C$ 

Figure 8. DC Current Gain



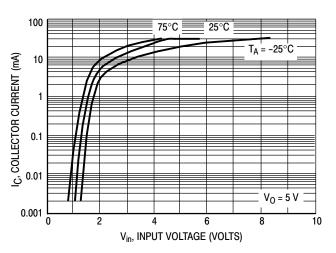


Figure 9. Output Capacitance

Figure 10. Output Current versus Input Voltage

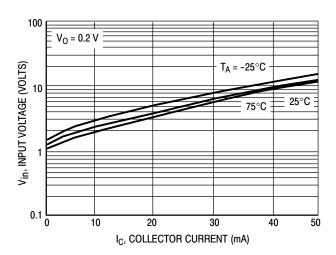


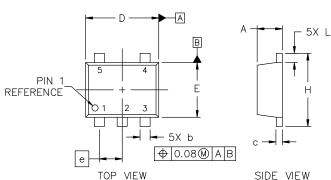
Figure 11. Input Voltage versus Output Current





#### SOT-553-5 1.60x1.20x0.55, 0.50P CASE 463B ISSUE D

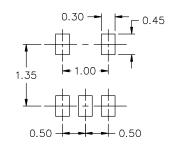
**DATE 21 FEB 2024** 



#### NOTES:

- DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
  - ALL DIMENSION ARE IN MILLIMETERS.
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

DIM	MILLIMETERS			
I DIIVI	MIN.	NOM.	MAX.	
А	0.50	0.55	0.60	
b	0.17	0.22	0.27	
С	0.08	0.13	0.18	
D	1.55	1.60	1.65	
Е	1.15	1.20	1.25	
е	0.50 BSC			
Н	1.55	1.60	1.65	
L	0.10	0.20	0.30	



#### RECOMMENDED MOUNTING FOOTPRINT\*

\* FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

# GENERIC MARKING DIAGRAM\*



XX = Specific Device Code

M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

STYLE 1: PIN 1. BASE 2. EMITTER 3. BASE 4. COLLECTOR 5. COLLECTOR	STYLE 2: PIN 1. CATHODE 2. COMMON ANODE 3. CATHODE 2 4. CATHODE 3 5. CATHODE 4	STYLE 3: PIN 1. ANODE 1 2. N/C 3. ANODE 2 4. CATHODE 2 5. CATHODE 1	STYLE 4: PIN 1. SOURCE 1 2. DRAIN 1/2 3. SOURCE 1 4. GATE 1 5. GATE 2	STYLE 5: PIN 1. ANODE 2. EMITTER 3. BASE 4. COLLECTOR 5. CATHODE
STYLE 6: PIN 1. EMITTER 2 2. BASE 2 3. EMITTER 1 4. COLLECTOR 1 5. COLLECTOR 2/BASE 1	STYLE 7: PIN 1. BASE 2. EMITTER 3. BASE 4. COLLECTOR 5. COLLECTOR	STYLE 8: PIN 1. CATHODE 2. COLLECTOR 3. N/C 4. BASE 5. EMITTER	STYLE 9: PIN 1. ANODE 2. CATHODE 3. ANODE 4. ANODE 5. ANODE	

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